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QN3103M3N

N-Channel 30V Fast Switching MOSFET

General Description

The QN3103M3N is a high performance trench N-channel MOSFET which utilizes extremely high cell density to provide low $R_{DS(on)}$ and gate charge characteristics. It is ideally suited to support synchronous buck converter applications.

The QN3103M3N meets RoHS and Green Product requirements while supporting full function reliability.

Features

- ✓ Advanced high cell density Trench technology
- ✓ Super Low Gate Charge
- ✓ Green Device Available

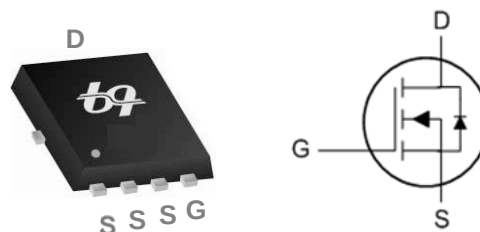
Product Summary

V_{DS}	$R_{DS(ON)}$ max ($V_{GS}=10V$)	I_D ($T_C=25^\circ C$)
30V	5.9m Ω	55A

Applications

- ✓ High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- ✓ Networking DC-DC Power System
- ✓ Load Switch

Pin Configuration



Ordering Information

Order Number	Package Type	Top Marking
QN3103M3N	PRPAK3X3	<div style="display: flex; align-items: center;"> <div style="border: 1px solid black; padding: 5px; margin-right: 10px;"> <p>Q N 3 1 0 3</p> <p>X X X X X</p> </div> <div> <p>Product Name</p> <p>Date Code</p> <p>Assy Code</p> <p>Sequence</p> <p>Weekly</p> <p>Yearly</p> </div> </div> <p>Pin 1 dot</p>

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Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, V_{GS} @ 10V ¹	55	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, V_{GS} @ 10V ¹	34	A
$I_D@T_A=25^{\circ}C$	Continuous Drain Current, V_{GS} @ 10V ¹	13	A
$I_D@T_A=70^{\circ}C$	Continuous Drain Current, V_{GS} @ 10V ¹	10	A
I_{DM}	Pulsed Drain Current ²	110	A
EAS	Single Pulse Avalanche Energy ³	54	mJ
I_{AS}	Avalanche Current	32.9	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation ⁴	27.7	W
$P_D@T_A=25^{\circ}C$	Total Power Dissipation ⁴	1.6	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	--	75	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	--	4.5	$^{\circ}C/W$

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N-Channel Electrical Characteristics

N-Channel Electrical Characteristics: (T _J =25 °C, unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	--	--	V
ΔBV _{DSS} / ΔT _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =1mA	--	0.011	--	V/°C
R _{DS(ON)}	Static Drain-Source	V _{GS} =10V, I _D =15A	--	4.7	5.9	mΩ
	On-Resistance ²	V _{GS} =4.5V, I _D =10A	--	6.9	9.0	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	--	2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		--	-4.2	--	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =24V, V _{GS} =0V, T _J =25°C	--	--	1	uA
		V _{DS} =24V, V _{GS} =0V, T _J =55°C	--	--	5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =10A	--	20	--	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	--	1.3	--	Ω
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =10V, I _D =10A	--	15.2	--	nC
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =4.5V, I _D =10A	--	7.7	--	
Q _{gs}	Gate-Source Charge		--	2.2	--	
Q _{gd}	Gate-Drain Charge		--	3.1	--	
t _{d(on)}	Turn-On Delay Time	V _{DS} =15V, V _{GS} =10V, R _G =3.3Ω, I _D =10A	--	7.0	--	ns
t _r	Rise Time		--	39.0	--	
t _{d(off)}	Turn-Off Delay Time		--	15.5	--	
t _f	Fall Time		--	5.8	--	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	--	837	--	pF
C _{oss}	Output Capacitance		--	475	--	
C _{rss}	Reverse Transfer Capacitance		--	63	--	

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Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	$V_{DD}=25V$, $L=0.1mH$, $I_{AS}=24A$	28.8	--	--	mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,6}	$V_G=V_D=0V$, Force Current	--	--	55	A
I_{SM}	Pulsed Source Current ^{2,6}		--	--	110	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V$, $I_S=1A$, $T_J=25^{\circ}C$	--	--	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=10A$, $di/dt=100A/\mu s$, $T_J=25^{\circ}C$	--	28.7	--	nS
Q_{rr}	Reverse Recovery Charge		--	12.3	--	nC

Note:

1. Test data conducted with surface mount attachment to 1 inch², FR-4 board utilizing 2oz copper
2. Pulse Test. Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. EAS data is a maximum rating. The test condition is $V_{DD}=25V$, $V_{GS}=10V$, $L=0.1mH$
4. The power dissipation is limited by a 150°C maximum junction temperature
5. The Min. value is 100% EAS tested guarantee
6. The data is theoretically the same as I_D and I_{DM} . In real applications, it will be limited by total power

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Typical Characteristics

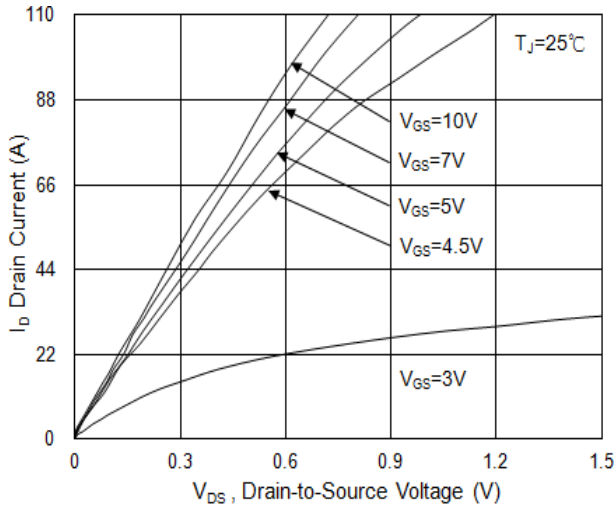


Fig.1: Typical Output Characteristics

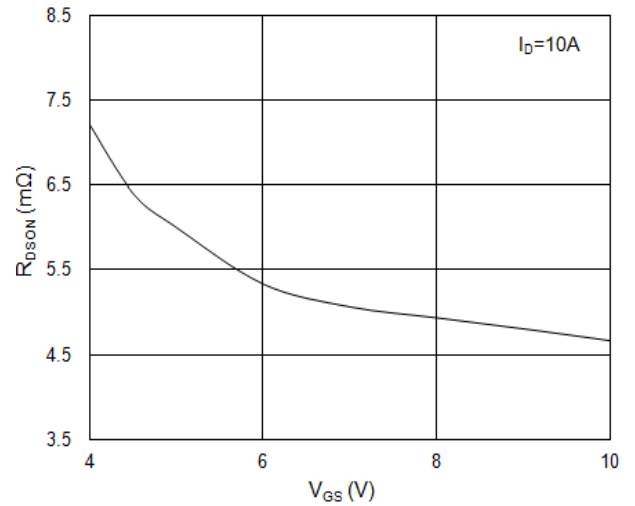


Fig.2: On-Resistance vs. Gate-Source

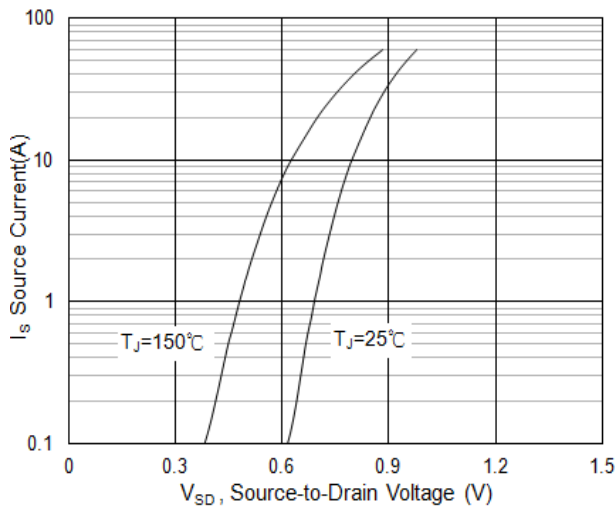


Fig.3: Forward Characteristics of Reverse

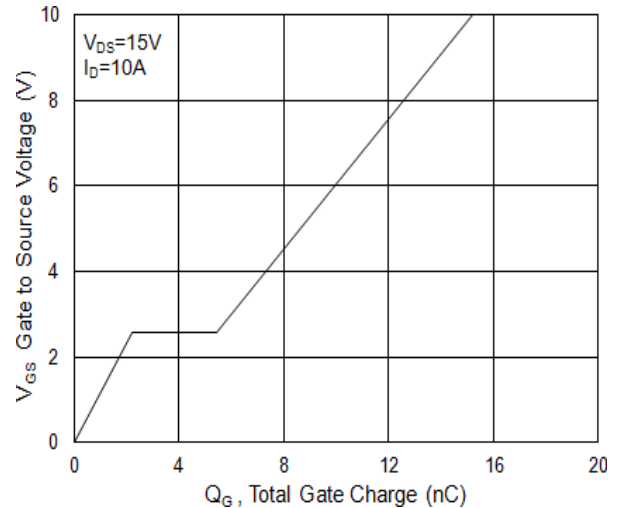


Fig.4: Gate-Charge Characteristics

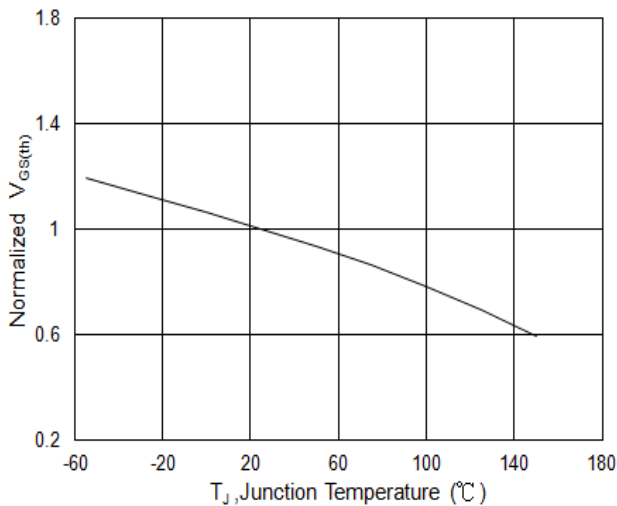


Fig.5: Normalized $V_{GS(th)}$ vs. T_J

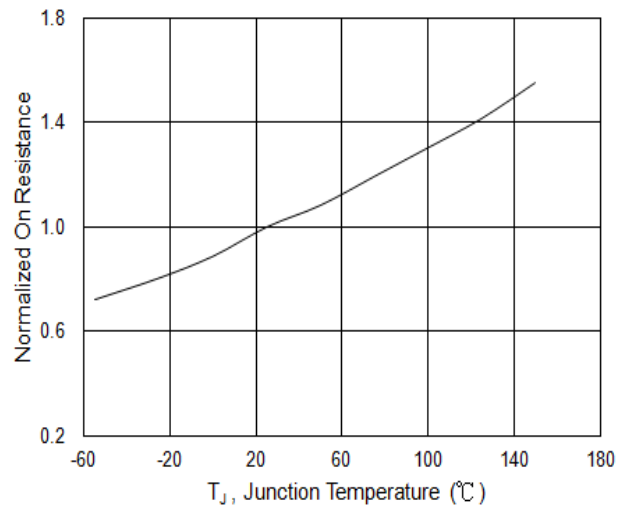


Fig.6: Normalized $R_{DS(on)}$ vs. T_J

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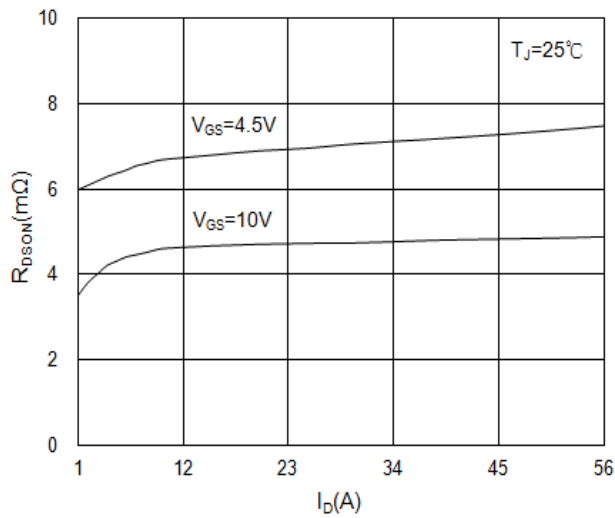


Fig.7: Drain-Source On-State Resistance

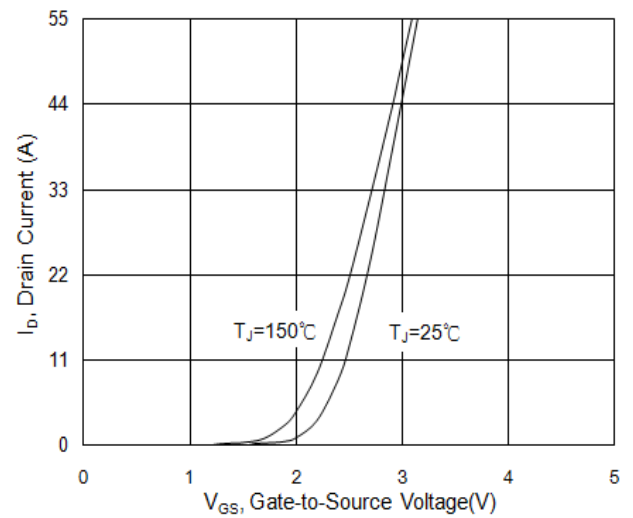


Fig.8: Transfer Characteristics

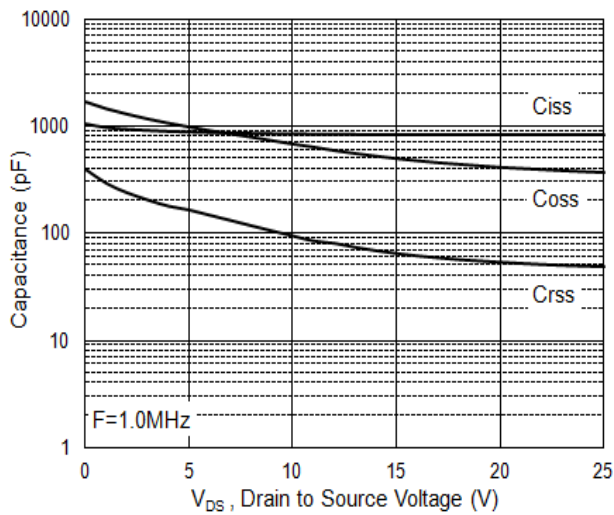


Fig.9: Capacitance

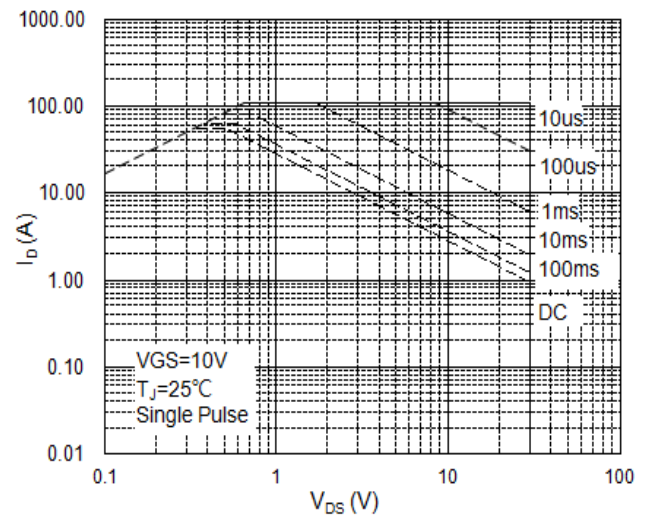


Fig.10: Safe Operating Area

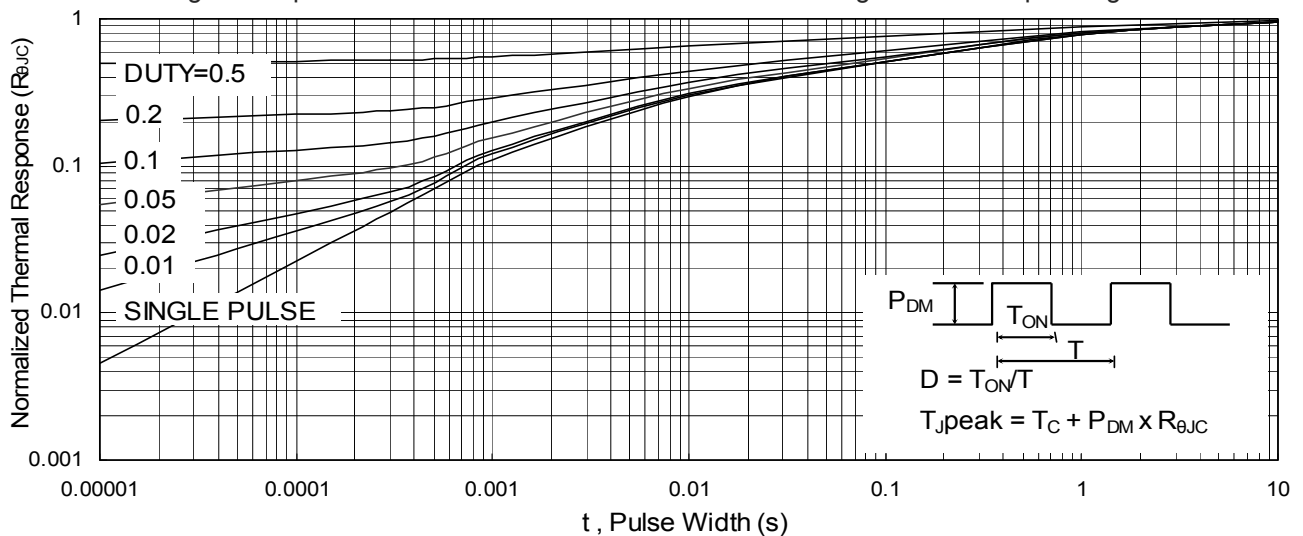


Fig.11: Transient Thermal Impedance

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